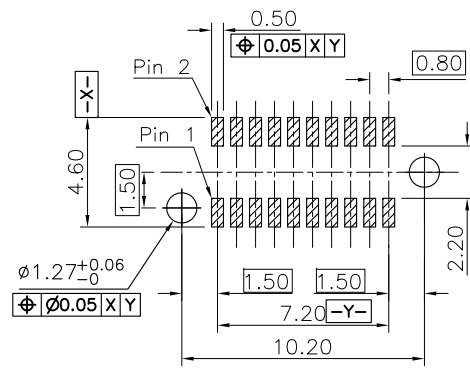
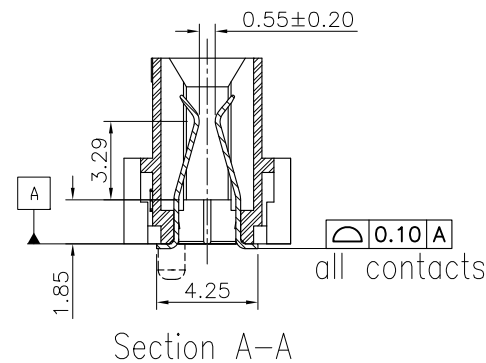
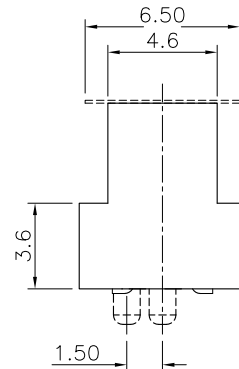
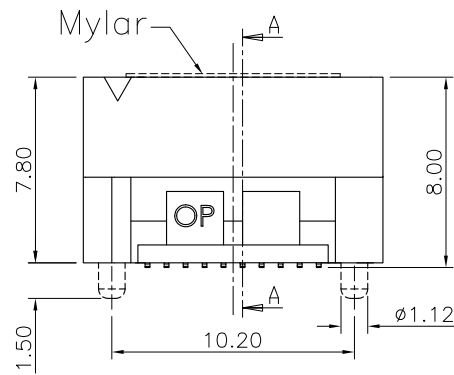
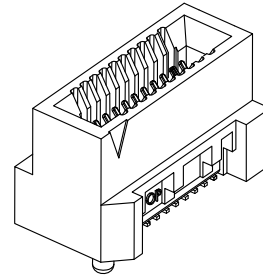
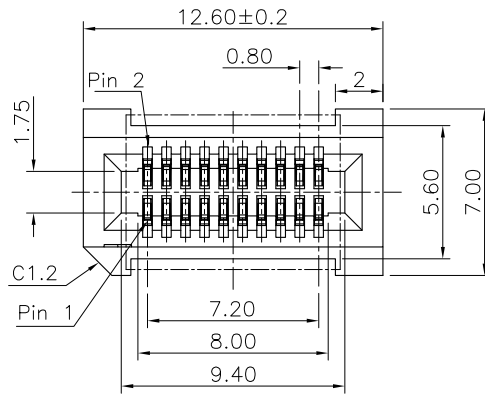


|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R12  |               | ECN211220 |       |



P.C. Board Layout  
(Tolerance  $\pm 0.05$ )

8206- 2 X 10 C xx D P T - S

Series: S: Mylar, P: Plastic Pad, Blank: Without Pad  
 Double Row  
 Position Per Row: T: Tape&Reel Packaging, U: Tube Packaging  
 C: Selective Gold Plated  
 00: 00 $\mu$ "  
 10: 10 $\mu$ "  
 15: 15 $\mu$ "  
 30: 30 $\mu$ "  
 P: With Post  
 N: Without Post  
 D: SMD Type

|                  |            |                |       |   |     |
|------------------|------------|----------------|-------|---|-----|
| Tolerances       | Dwg.No.    | 8206-D0000-001 |       | Title:  |     |
| x = $\pm 0.50$   | Projection |                |       | 8206 Series<br>Edge Card Connector<br>0.80mm (0.0315") Pitch SMD Type |     |
| .x = $\pm 0.25$  | Unit       | mm             | Scale |   | 1:1 |
| .xx = $\pm 0.15$ | Drawn By   | ZY 12/22'21    |       |   |     |

|                                     |     |                   |     |
|-------------------------------------|-----|-------------------|-----|
| <b>OUPIN</b>                        |     |                   |     |
| OUPIN ELECTRONIC(KUNSHAN) CO., LTD. |     |                   |     |
| P/N:                                |     | 8206-2X10CxxDPT-S |     |
| SHEET                               | 1/2 | Ver.No.           | R12 |

**Material and Plating :**

Housing: LCP, UL94V-0,Black.  
 Contacts: High performance Copper Alloy  
 Gold Plated on Contact Area and 80u" Min Tin Plated on solder tail over Nickel 50u" Min.

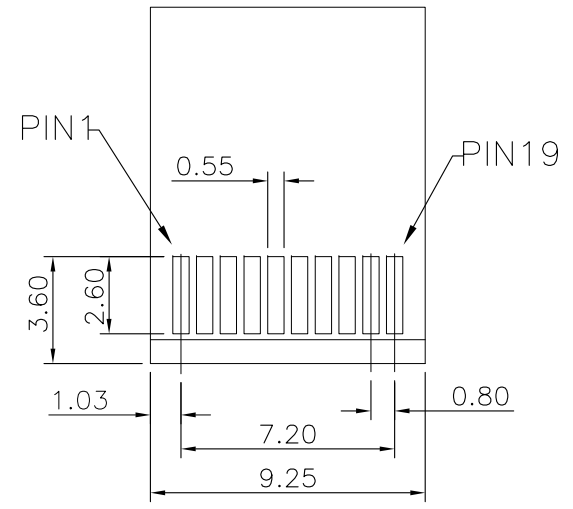
**Electrical Characteristics:**

Current Rating: 3.1 AMP.  
 Dielectric Withstanding Voltage: AC 600V For 1 minute.  
 Insulator Resistance: 6000M $\Omega$  min. at DC 250V.  
 Contact Resistance: 8.4m $\Omega$  max. at DC 100mA.  
 Operating Temperature: -55°C~+125°C.

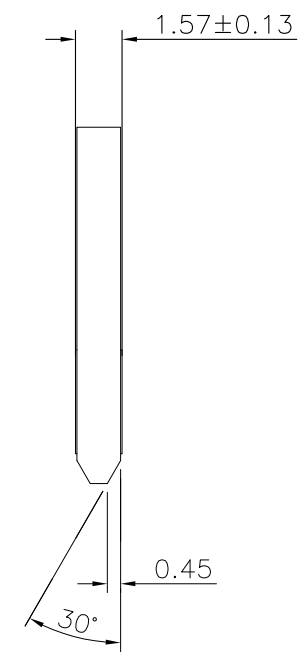
**\*RoHS Compliant**

Insertion Depth: 3.15mm To 5.55mm.  
 Speed: 28+Gbps @-3dB.

|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R12  |               | ECN211220 |       |

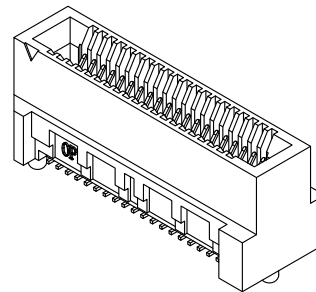
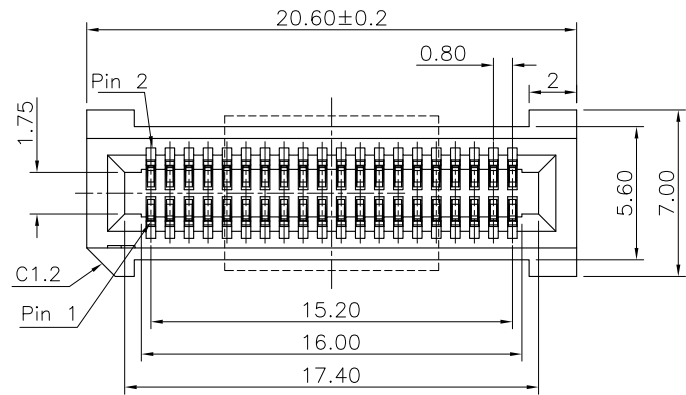


RECOMMENDED MATTING BOARD FOOTPRINT  
(Tolerance: ±0.05)



|             |            |             |                |                                    |                                 |                        |   |         |     |
|-------------|------------|-------------|----------------|------------------------------------|---------------------------------|------------------------|---|---------|-----|
| Tolerances  |            | Dwg.No.     | 8206-D0000-001 |                                    | Title:                          |                        | <b>OUPIN</b><br>OUPIN ELECTRONIC(KUNSHAN) CO., LTD. |         |     |
| x = ±0.50   | Projection |             |                | 8206 Series<br>Edge Card Connector |                                 | P/N: 8206-2X10CxxDPT-S |   |         |     |
| .x = ±0.25  | Unit       | mm          | Scale          | 1:1                                | 0.80mm (0.0315") Pitch SMD Type |                        | SHEET   |         |     |
| .xx = ±0.15 | Drawn By   | ZY 12/22'21 |                | ©                                  |                                 | 2/2                    |   | Ver.No. | R12 |

|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R8   |               | ECN211220 |       |



**Material and Plating :**

**Housing:** LCP,UL94V-0,BLACK.

**Contacts:** High performance Copper Alloy

Gold Plated on Contact Area and 80u" Min Tin Plated on solder tail over Nickel 50u" Min.

**Electrical Characteristics:**

**Current Rating:** 3.1 AMP.

**Dielectric Withstanding Voltage:** AC 600V For 1 minute.

**Insulator Resistance:** 6000MΩ min. at DC 250V.

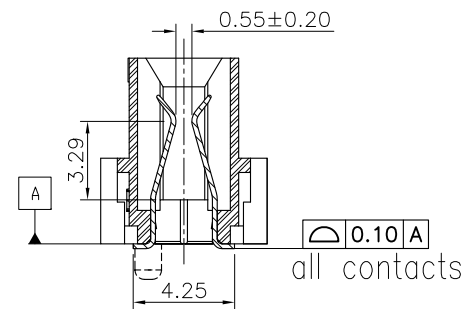
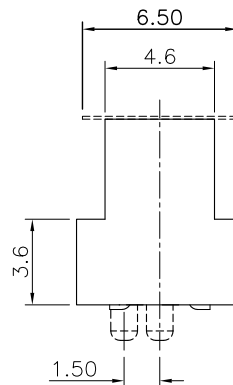
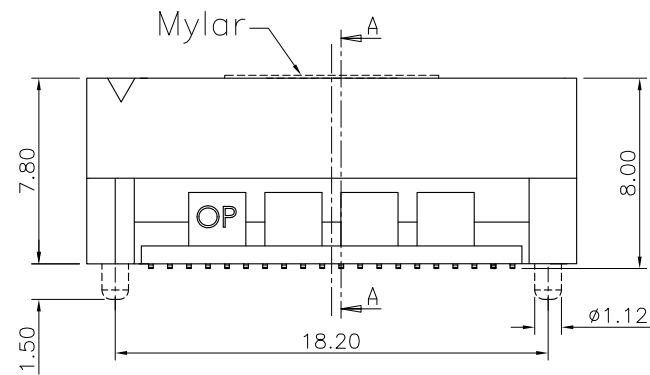
**Contact Resistance:** 8.4mΩ max. at DC 100mA.

**Operating Temperature:** -55°C~+125°C.

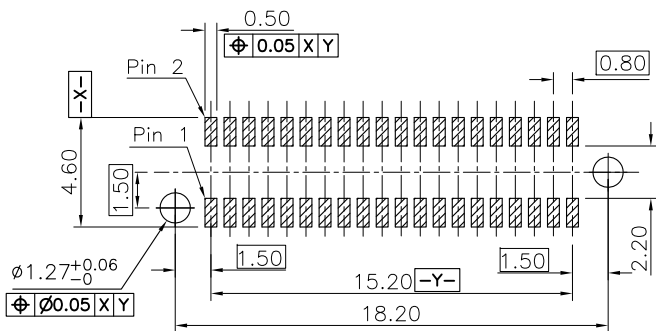
**\*RoHS Compliant**

**Insertion Depth:** 3.15mm To 5.55mm.

**Speed:** 28+Gbps @-3dB.



Section A-A



P.C. Board Layout  
(Tolerance  $\pm 0.05$ )

Series **8206- 2 X 20 C xx D P x - x**

- S: Mylar
- P: Plastic Pad
- Blank: Without Pad , Without Mylar

Position Per Row

- T: Tape&Reel Packaging
- U: Tube Packaging
- A: Tray Packaging

C: Selective Gold Plated

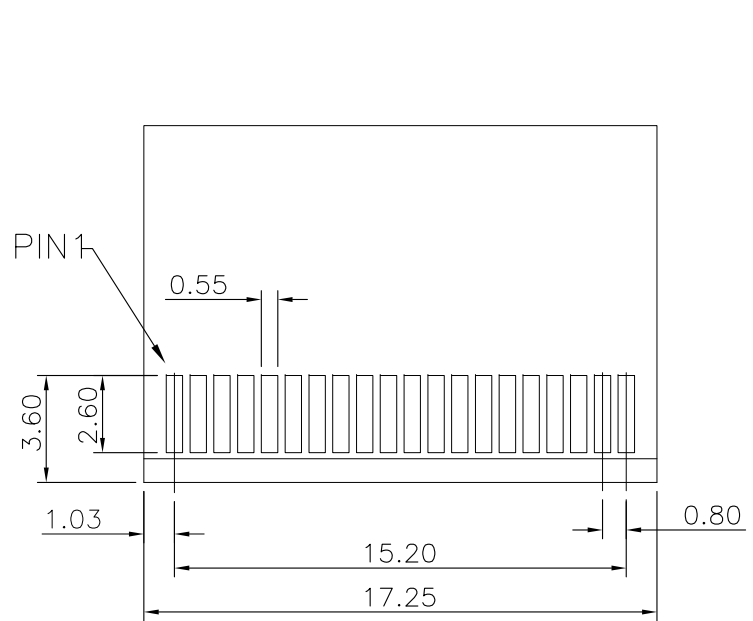
10: 10u"  
30: 30u"

- P: With Post
- N: Without Post
- D: SMD Type

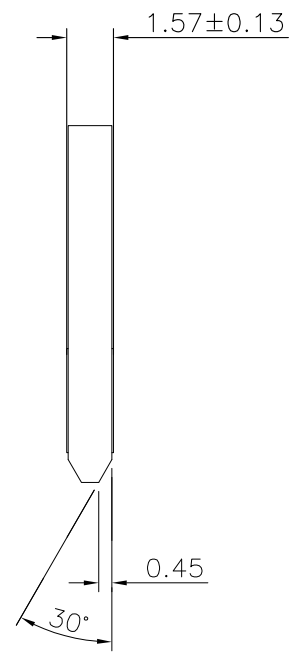
|                  |            |                |                                 |  |
|------------------|------------|----------------|---------------------------------|--|
| Tolerances       | Dwg.No.    | 8206-D0000-007 | Title:                          |  |
| x = $\pm 0.50$   | Projection |                | 8206 Series                     |  |
| .x = $\pm 0.25$  | Unit       | mm             | Edge Card Connector             |  |
| .xx = $\pm 0.15$ | Scale      | 1:1            | 0.80mm (0.0315") Pitch SMD Type |  |
|                  | Drawn By   | ZY 12/22'21    |                                 |  |



|                                     |     |                   |    |
|-------------------------------------|-----|-------------------|----|
| <b>OUPIN</b>                        |     |                   |    |
| OUPIN ELECTRONIC(KUNSHAN) CO., LTD. |     |                   |    |
| P/N:                                |     | 8206-2X20CxxDPx-x |    |
| SHEET                               | 1/2 | Ver.No.           | R8 |

|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R8   |               | ECN211220 |       |

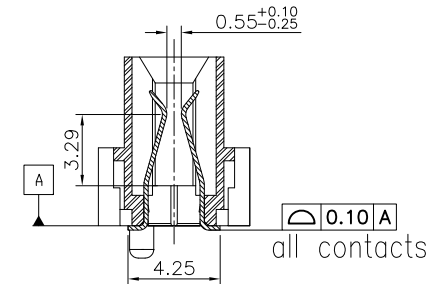
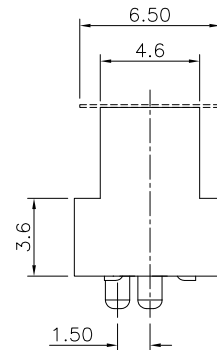
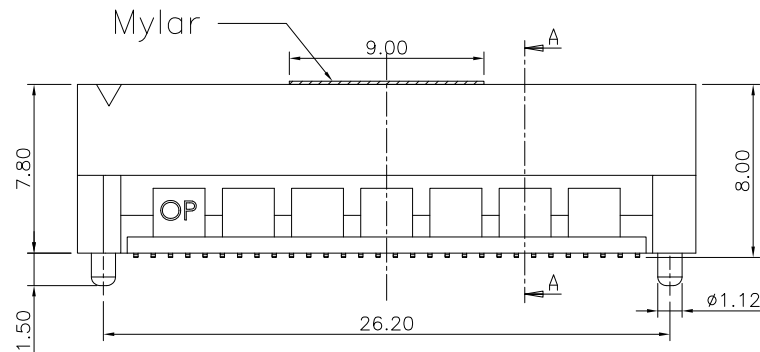
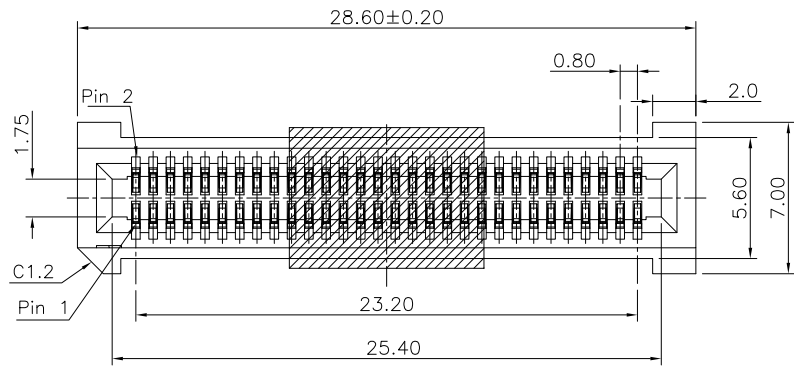


**RECOMMENDED MATTING BOARD FOOTPRINT**  
(Tolerance: ±0.05)

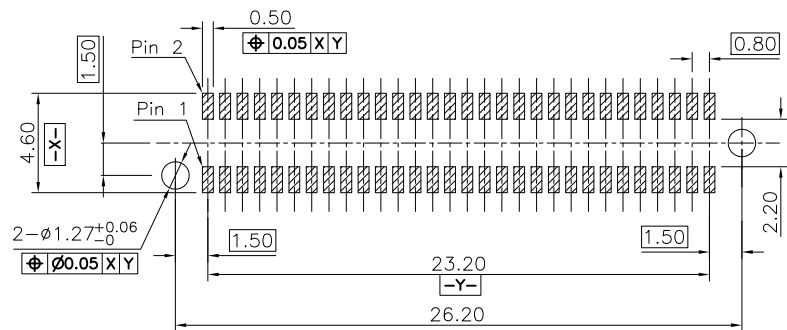


|   |   |                  |                                    |  |  |
|---|---|------------------|------------------------------------|--|--|
| <b>Tolerances</b><br>x = ±0.50<br>.x = ±0.25<br>.xx = ±0.15 | <b>Dwg.No.</b> 8206-D0000-007   |                  | <b>Title:</b>                      |  | <br><b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b> |
|   | <b>Projection</b>  |                  | 8206 Series<br>Edge Card Connector |  |  |
|   | <b>Unit</b> mm  | <b>Scale</b> 1:1 | 0.80mm (0.0315") Pitch SMD Type    |  | <b>SHEET</b> 2/2   |
|   | <b>Drawn By</b> ZY 12/22'21   |                  |                                    |  |  |
|   |   |                  |                                    |  | <b>R8</b>  |

|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R1   |               | ECN220715 |       |



Section A-A



P.C. Board Layout  
(Tolerance  $\pm 0.05$ )

8206- 2 X 30 C 30 D P T - S

Series ——— S: Mylar  
 Double Row ——— T: Tape&Reel Packaging  
 Position Per Row ——— P: With Post  
 C: Selective Gold Plated ——— D: SMD Type  
 00: 00 $\mu$ "  
 10: 10 $\mu$ "  
 15: 15 $\mu$ "  
 30: 30 $\mu$ "

|                  |            |                |                                 |  |     |         |    |
|------------------|------------|----------------|---------------------------------|--|-----|---------|----|
| Tolerances       | Dwg.No.    | 8206-D0000-009 | Title:                          | <br>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.<br>P/N: 8206-2X30C30DPT-S |     |         |    |
| x = $\pm 0.50$   | Projection |                | 8206 Series                     |  |     |         |    |
| .x = $\pm 0.25$  | Unit       | mm             | Edge Card Connector             | SHEET  | 1/2 | Ver.No. | R1 |
| .xx = $\pm 0.15$ | Scale      | 1:1            | 0.80mm (0.0315") Pitch SMD Type |  |     |         |    |
|                  | Drawn By   | GYJ 07/12'22   |                                 |  |     |         |    |

**Material and Plating:**

Housing: LCP, UL94V-0, BLACK.  
 Signal Contacts : High Performance Copper Alloy.  
 Gold plated on Contact Area and 80u" Min  
 Tin Plated on Solder Tail over nickel 50u" Min .

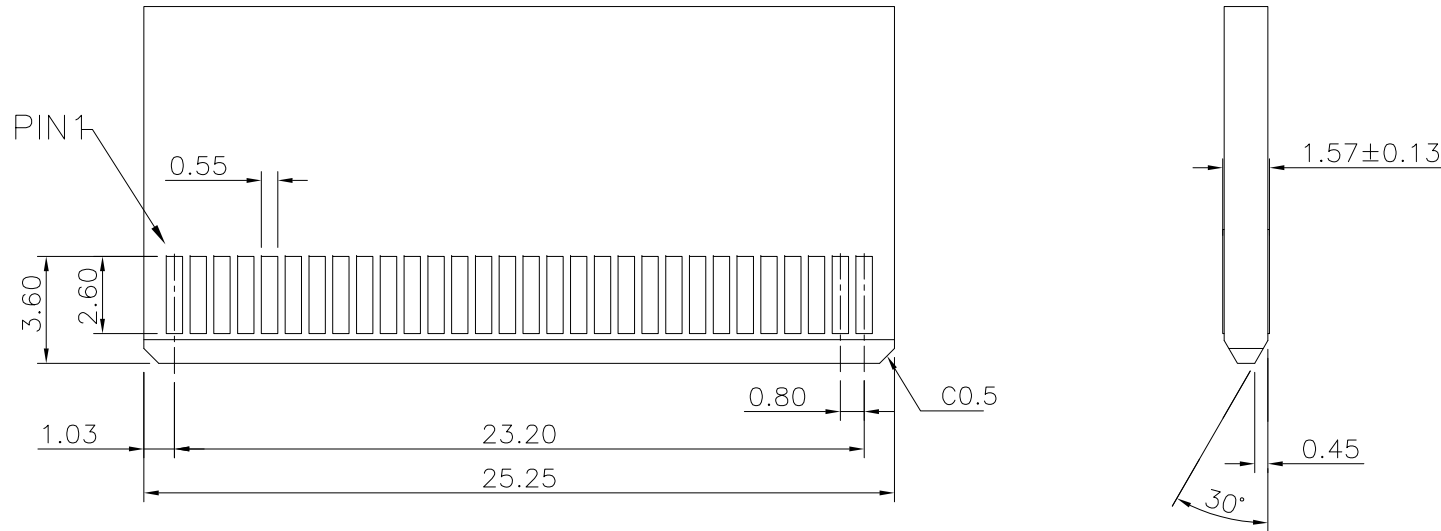
**Electrical Characteristics:**

Current Rating: 3.1 AMP.  
 Dielectric Withstanding Voltage: AC 600V For 1 minute.  
 Insulator Resistance: 6000M $\Omega$  min. at DC 250V.  
 Contact Resistance: 8.4m $\Omega$  max. at DC 100mA.  
 Operating Temperature: -55 $^{\circ}$ C~+125 $^{\circ}$ C.

**\*RoHS Compliant**

Insertion Depth: 3.15mm To 5.55mm.  
 Speed: 28+Gbps @-3dB.

|      |               |           |       |
|------|---------------|-----------|-------|
| REV. | SPECIFICATION | ECN NO.   | APPD. |
| R1   |               | ECN220715 |       |



RECOMMENDED MATING BOARD FOOTPRINT  
(Tolerance:±0.05)

|  |              |                |       |   |                                     |                        |    |  |
|--|--------------|----------------|-------|---|-------------------------------------|------------------------|----|--|
| Tolerances<br>x = ±0.50<br>.x = ±0.25<br>.xx = ±0.15 | Dwg.No.      | 8206-D0000-009 |       | Title:<br>8206 Series<br>Edge Card Connector<br>0.80mm (0.0315") Pitch SMD Type | <b>OUPIN</b>                        |                        |    |  |
|  | Projection   | ⊕ ↗            |       |   | OUPIN ELECTRONIC(KUNSHAN) CO., LTD. |                        |    |  |
|  | Unit         | mm             | Scale |   | 1:1                                 | P/N: 8206-2X30C30DPT-S |    |  |
| Drawn By   | GYJ 07/12'22 |                | Ⓢ     | SHEET   | 2/2                                 | Ver.No.                | R1 |  |